

sectional view taken along the line 9-9 of FIG. 8, and FIG. 10 is a developed sectional view showing a detailed constitution of the electromagnetic shielding structure shown in FIG. 9. In FIGS. 7 to 10, inclusive, reference numeral 21 designates a semiconductor chip, 21A an external electrode (bonding pad) for the semiconductor chip 21, 22 an electromagnetic shielding film, 23 an insulating film (polyimide film), 31 a solder ball, 32 leads (copper foil wiring) in a package having BGA structure of CSP type, 33 a polyimide film (insulating film) after having worked a cavity for mounting solder ball, 34 an adhesive of epoxy or the like base resin, 35 a cavity for mounting solder ball, and 36 a thermoplastic adhesive prepared from thermoplastic polyimide or B-stage epoxy, respectively.

IN THE CLAIMS:

Please cancel claim 2 without prejudice or disclaimer.

Please amend claims 1, 5, and 6 as follows:

1. A wiring board for a semiconductor device, comprising
a predetermined wiring section being disposed on an insulation board; and
an electromagnetic shielding film being placed at a position close to said wiring
section,
wherein a distance defined between said wiring section and said electromagnetic
shielding film is 150 μm or less, a volume specific resistance of said electromagnetic
shielding film is 30 $\mu\Omega\cdot\text{cm}$ or less at room temperature, and
wherein, over an applicable frequency between about 10 MHz to 15GHz, an
inductance of said wiring section and inductive cross talk are reduced.